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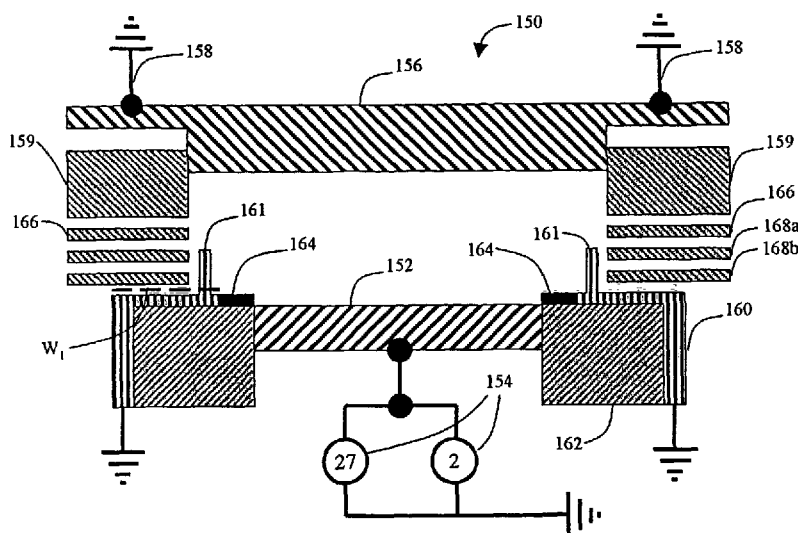
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(54) Title: A PLASMA PROCESSING APPARATUS AND METHOD



(57) Abstract: The present invention includes a system and method for confining plasma within a plasma processing chamber. The plasma processing apparatus comprises a first electrode (152), a power generator (154), a second electrode (156), at least one confinement ring (166), and a ground extension (160) surrounding the first electrode (152). The first electrode (152) is configured to receive a workpiece and has an associated first electrode area. The power generator (154) is operatively coupled to the first electrode (152), and the power generator (154) is configured to generate RF power that is communicated to the first electrode (152). The second electrode (156) is disposed at a distance from the first electrode (152). The second electrode (156) is configured to provide a complete electrical circuit for RF power communicated from the first electrode (152). Additionally, the second electrode (156) has a second electrode area that is greater than the first electrode area. At least one confinement ring (166) is configured to assist confine the plasma.



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